



US00D571739S

(12) **United States Design Patent**
Hosaka

(10) **Patent No.:** **US D571,739 S**
(45) **Date of Patent:** **** Jun. 24, 2008**

(54) **SEMICONDUCTOR WAFER DELIVERY APPARATUS**

(75) Inventor: **Hiroki Hosaka**, Nirasaki (JP)

(73) Assignee: **Tokyo Electron Limited**, Tokyo (JP)

(**) Term: **14 Years**

(21) Appl. No.: **29/242,544**

(22) Filed: **Nov. 14, 2005**

(30) **Foreign Application Priority Data**

Aug. 12, 2005 (JP) 2005-023557

(51) **LOC (8) Cl.** **13-03**

(52) **U.S. Cl.** **D13/182**

(58) **Field of Classification Search** D13/182;
134/110; 396/611; 414/331.15, 411, 416.03;
700/213

See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

5,636,960	A *	6/1997	Hiroki et al.	414/781
5,740,059	A *	4/1998	Hirata et al.	700/213
5,772,386	A *	6/1998	Mages et al.	414/411
5,826,129	A *	10/1998	Hasebe et al.	396/611
6,132,160	A *	10/2000	Iwai	414/416.03
6,234,738	B1 *	5/2001	Kimata et al.	414/416.03
6,811,370	B2 *	11/2004	Buermann	414/416.03
6,846,149	B2 *	1/2005	Savage et al.	414/416.03
2002/0044860	A1 *	4/2002	Hayashu et al.	414/416.03
2002/0182040	A1 *	12/2002	Kimura et al.	414/331.04

2002/0197138	A1 *	12/2002	Cho et al.	414/416.03
2003/0133776	A1 *	7/2003	Lee	414/416.03
2004/0265100	A1 *	12/2004	Ohkawara et al.	414/416.03
2005/0220581	A1 *	10/2005	Chuang et al.	414/416.03
2007/0031222	A1 *	2/2007	Hosaka et al.	414/416.03

* cited by examiner

Primary Examiner—Selina Sikder

(74) *Attorney, Agent, or Firm*—Oblon, Spivak, McClelland, Maier & Neustadt, P.C.

(57) **CLAIM**

The ornamental design for a semiconductor wafer delivery apparatus, as shown and described.

DESCRIPTION

FIG. 1 is a front elevational view of a semiconductor wafer delivery apparatus, showing my design;

FIG. 2 is a rear elevational view thereof;

FIG. 3 is a left side elevational view thereof;

FIG. 4 is a right side elevational view thereof;

FIG. 5 is a top plan view thereof;

FIG. 6 is a bottom plan view thereof;

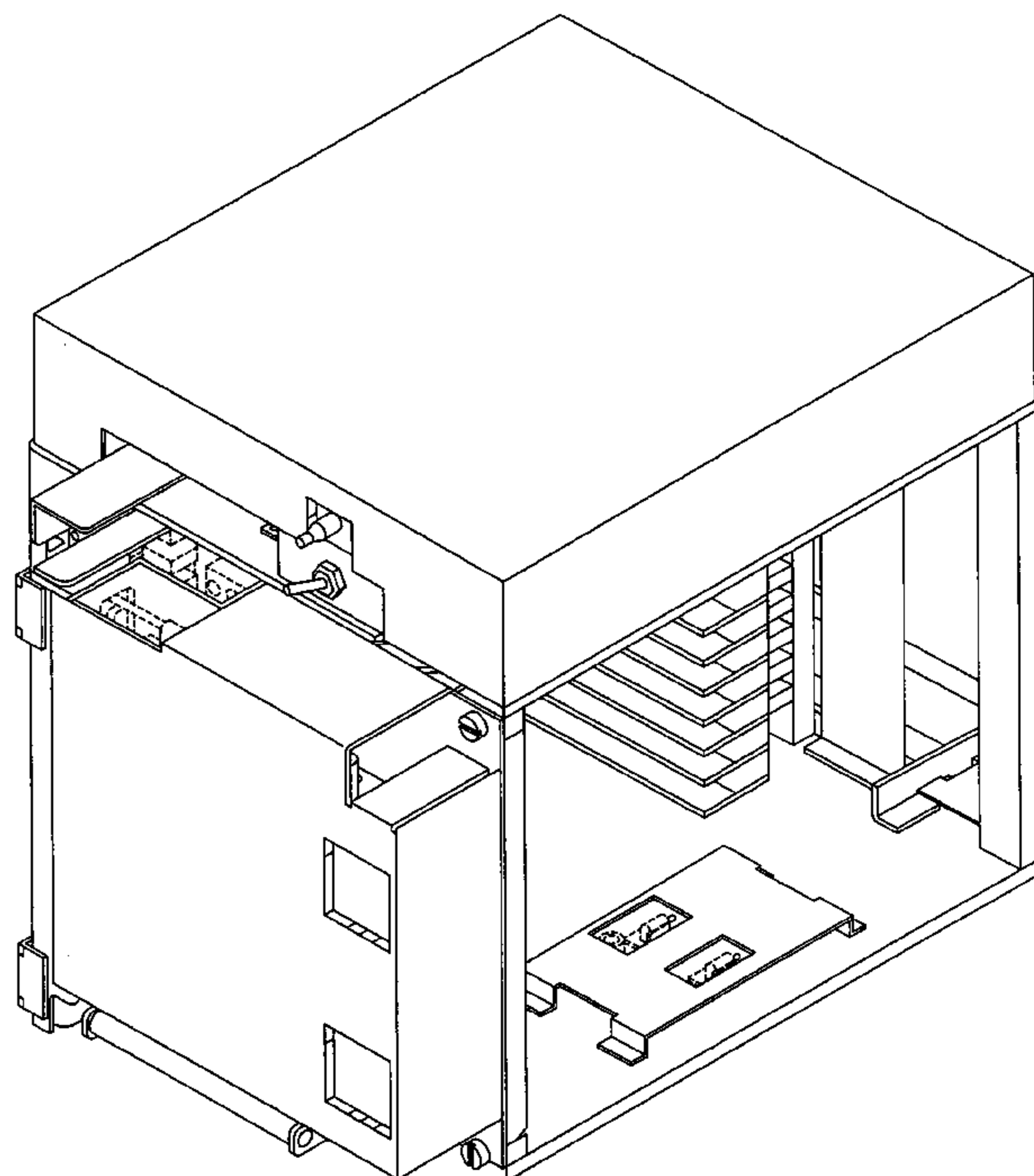
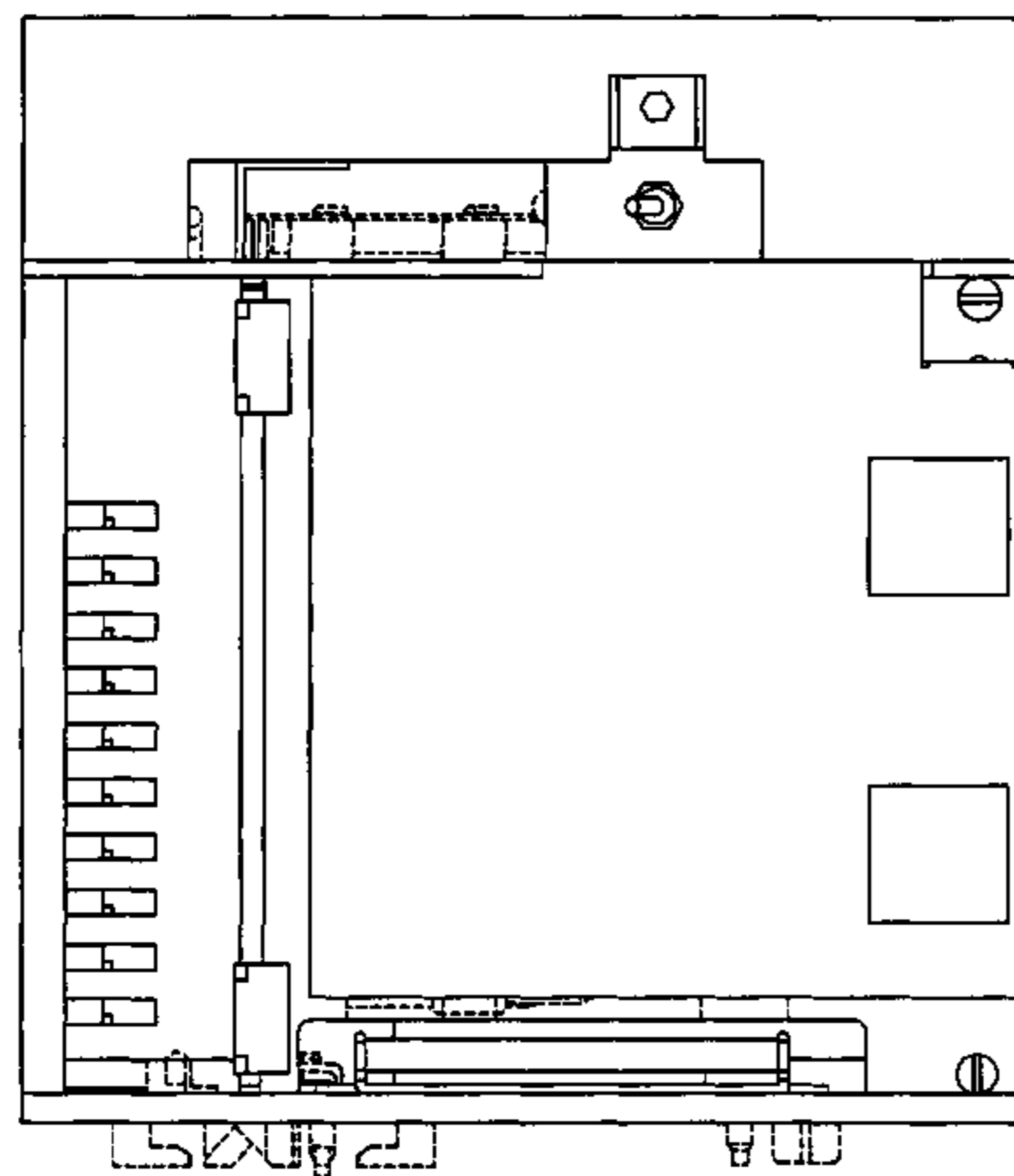
FIG. 7 is a cross-sectional view taken along line 7—7 in FIG. 1;

FIG. 8 is a top, front and right perspective view thereof; and,

FIG. 9 is a top and left rear perspective view thereof.

The broken line showing in the figures is for illustrative purposes only and forms no part of the claimed design.

1 Claim, 9 Drawing Sheets



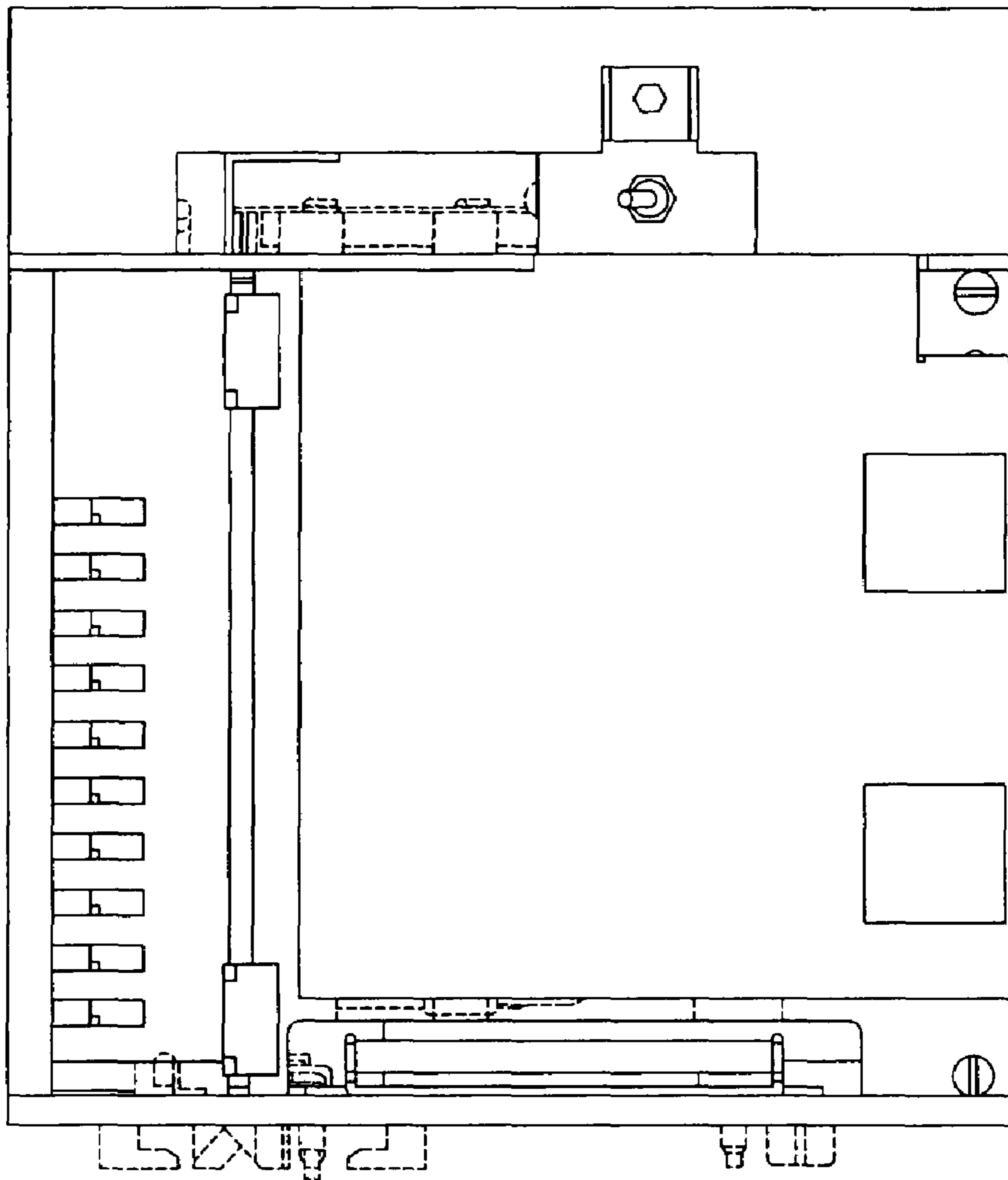


Fig. 1

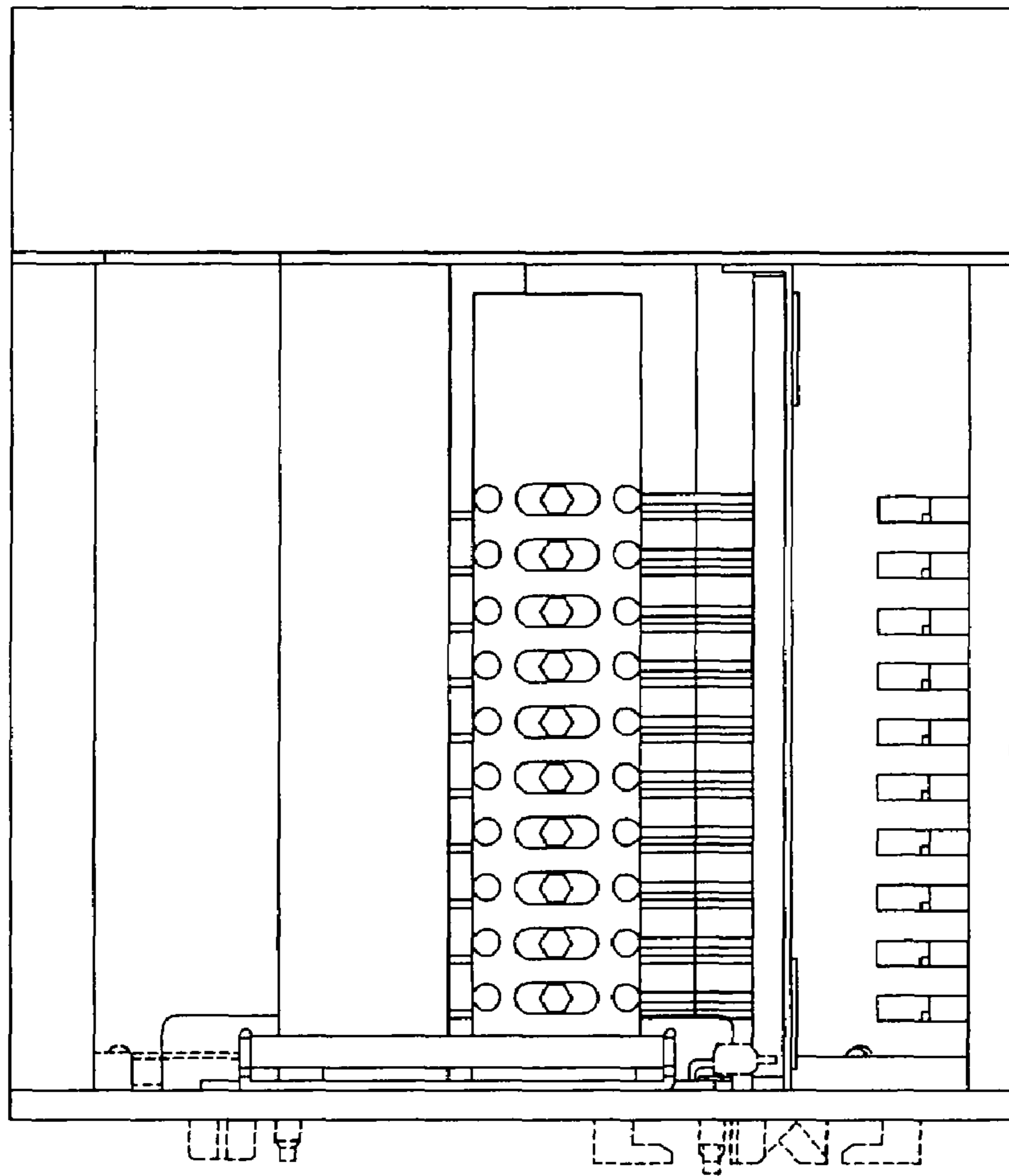


Fig. 2

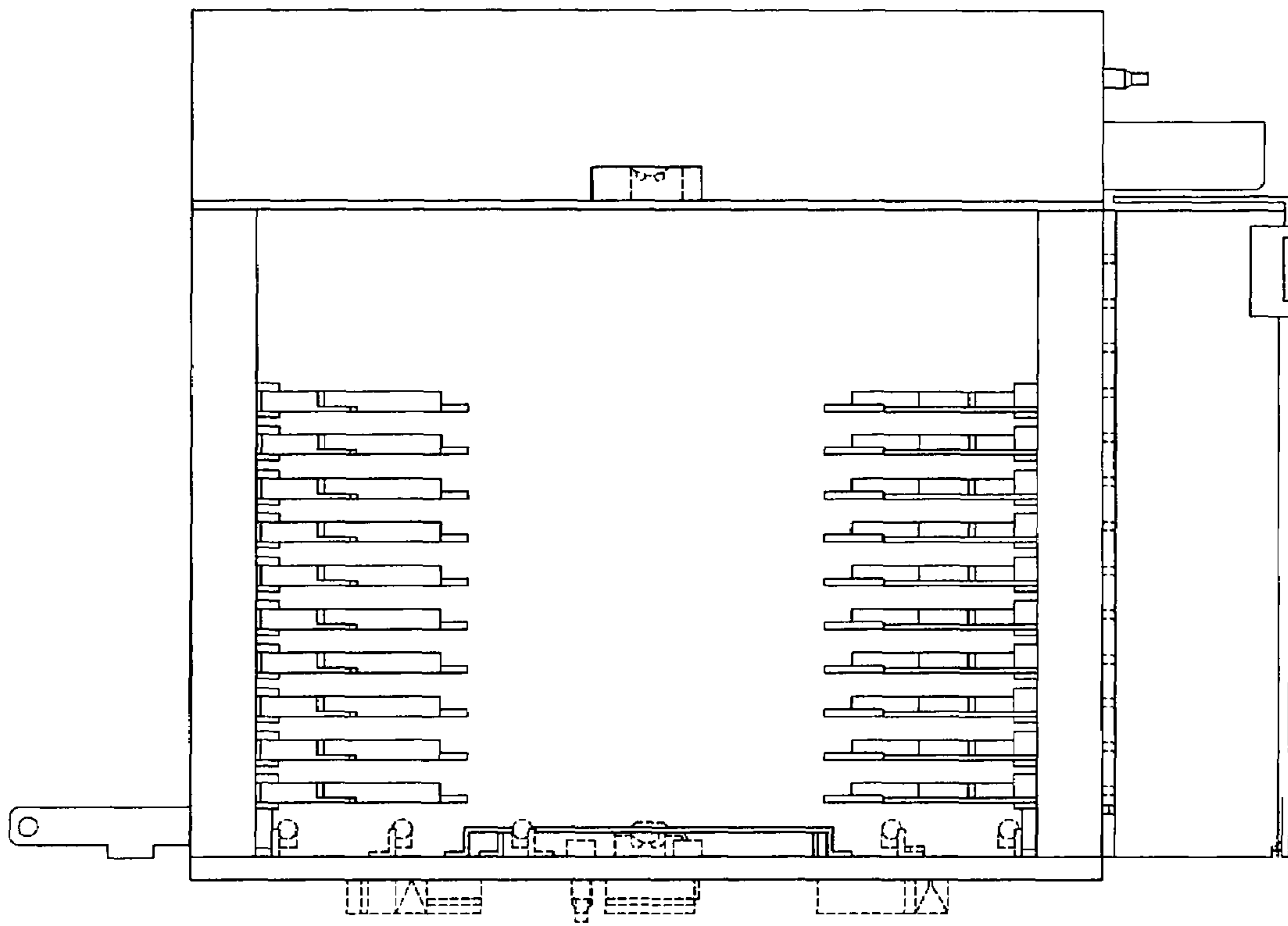


Fig. 3

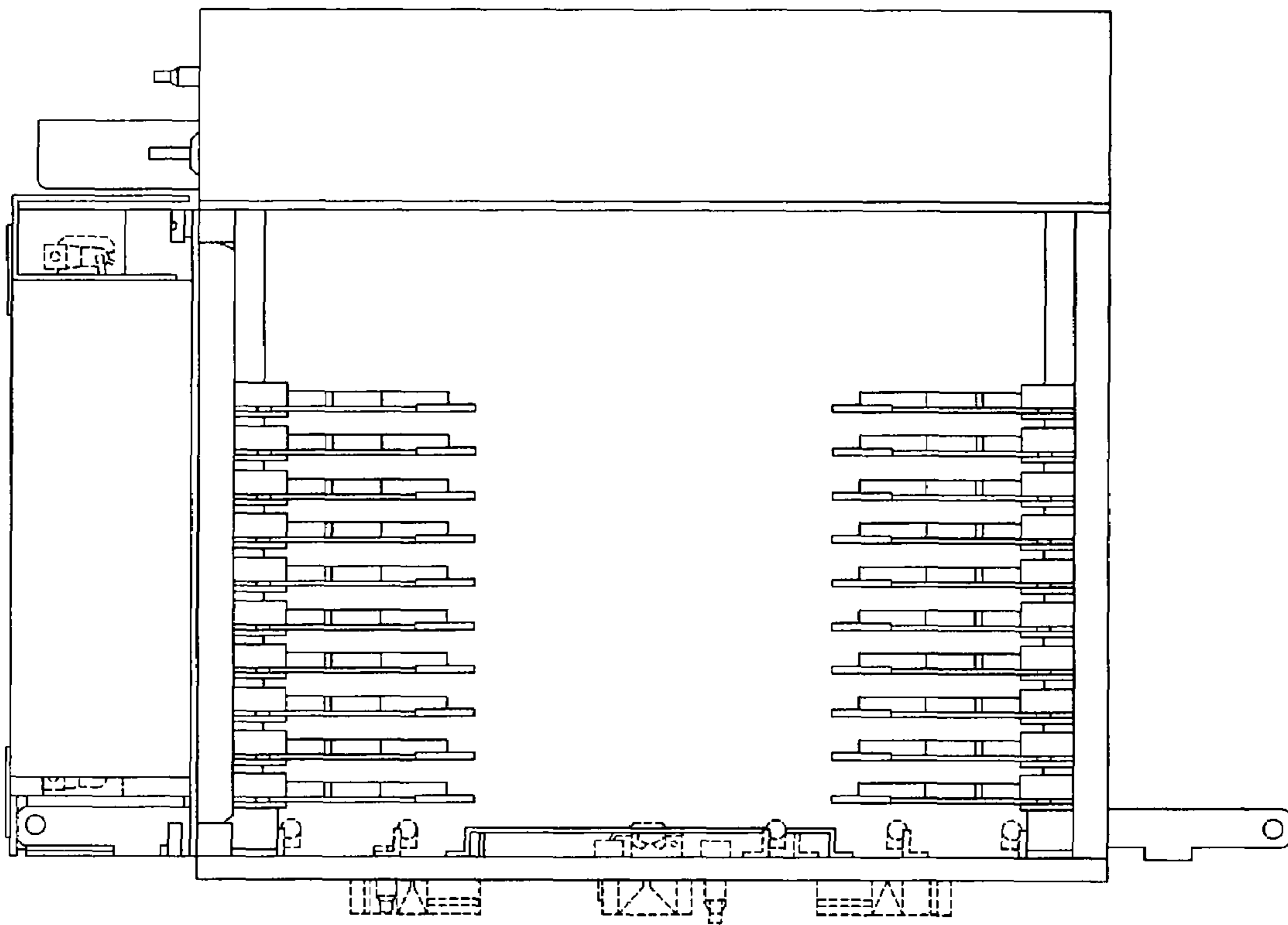


Fig. 4

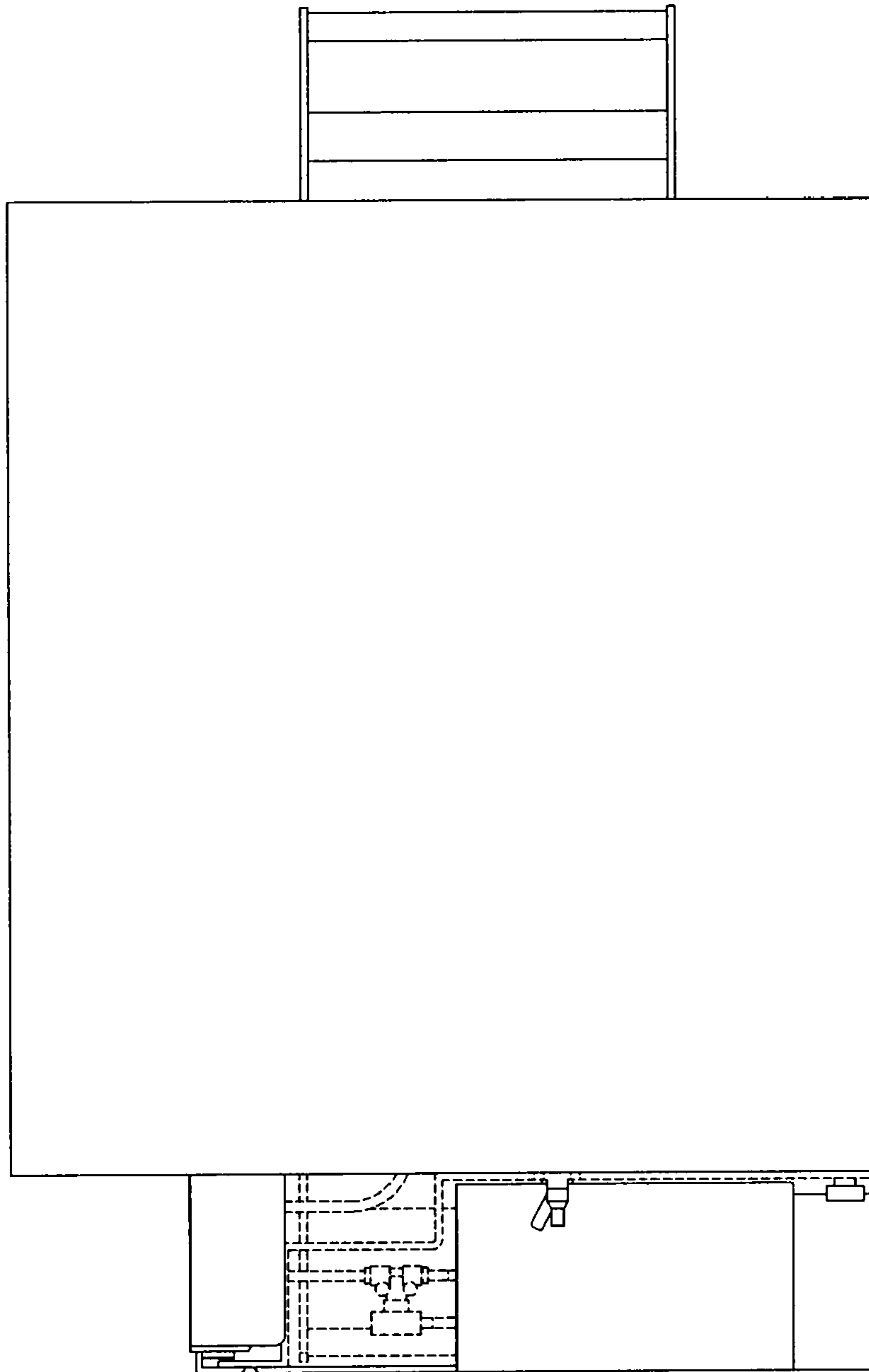


Fig. 5

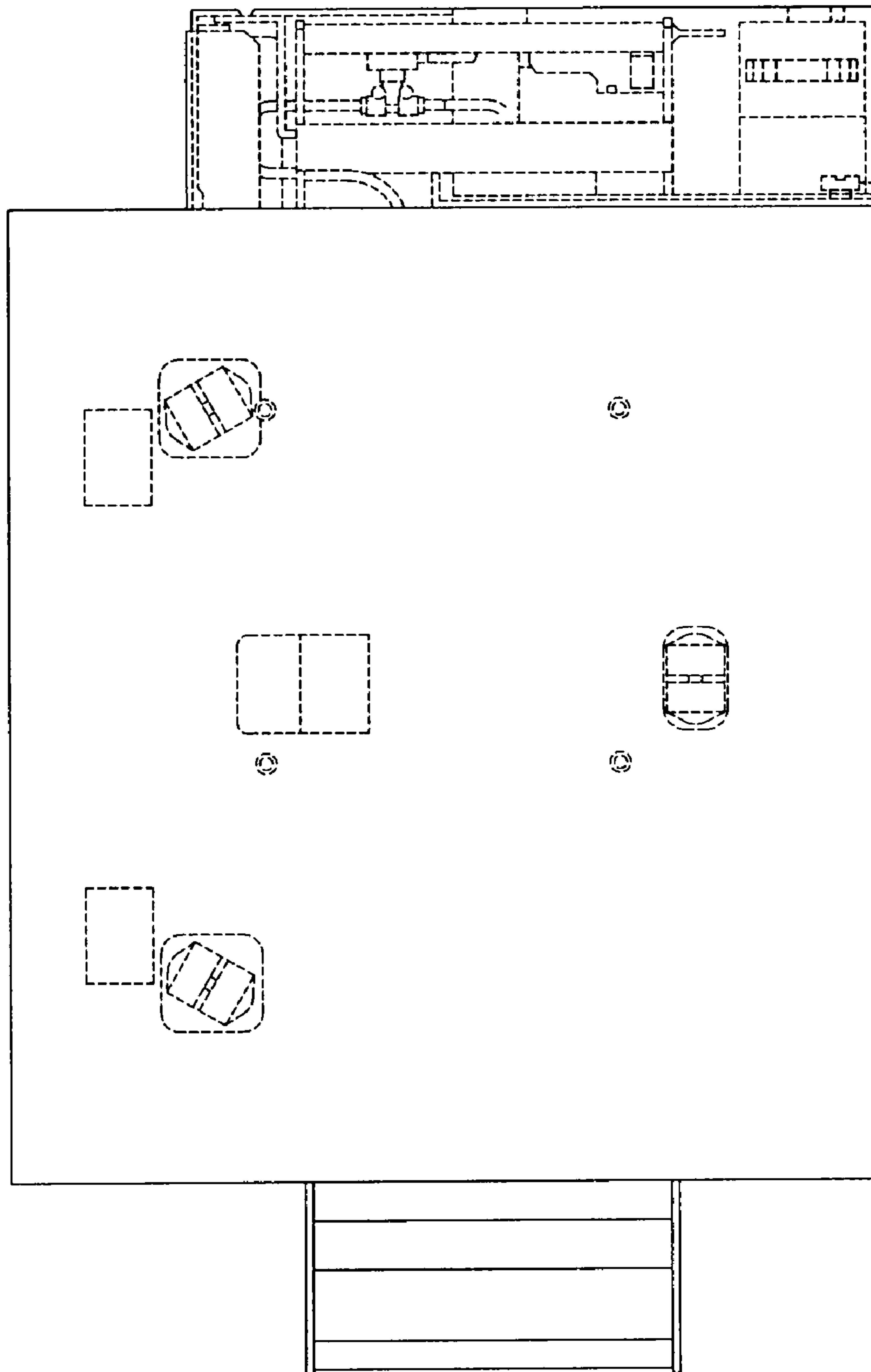


Fig. 6

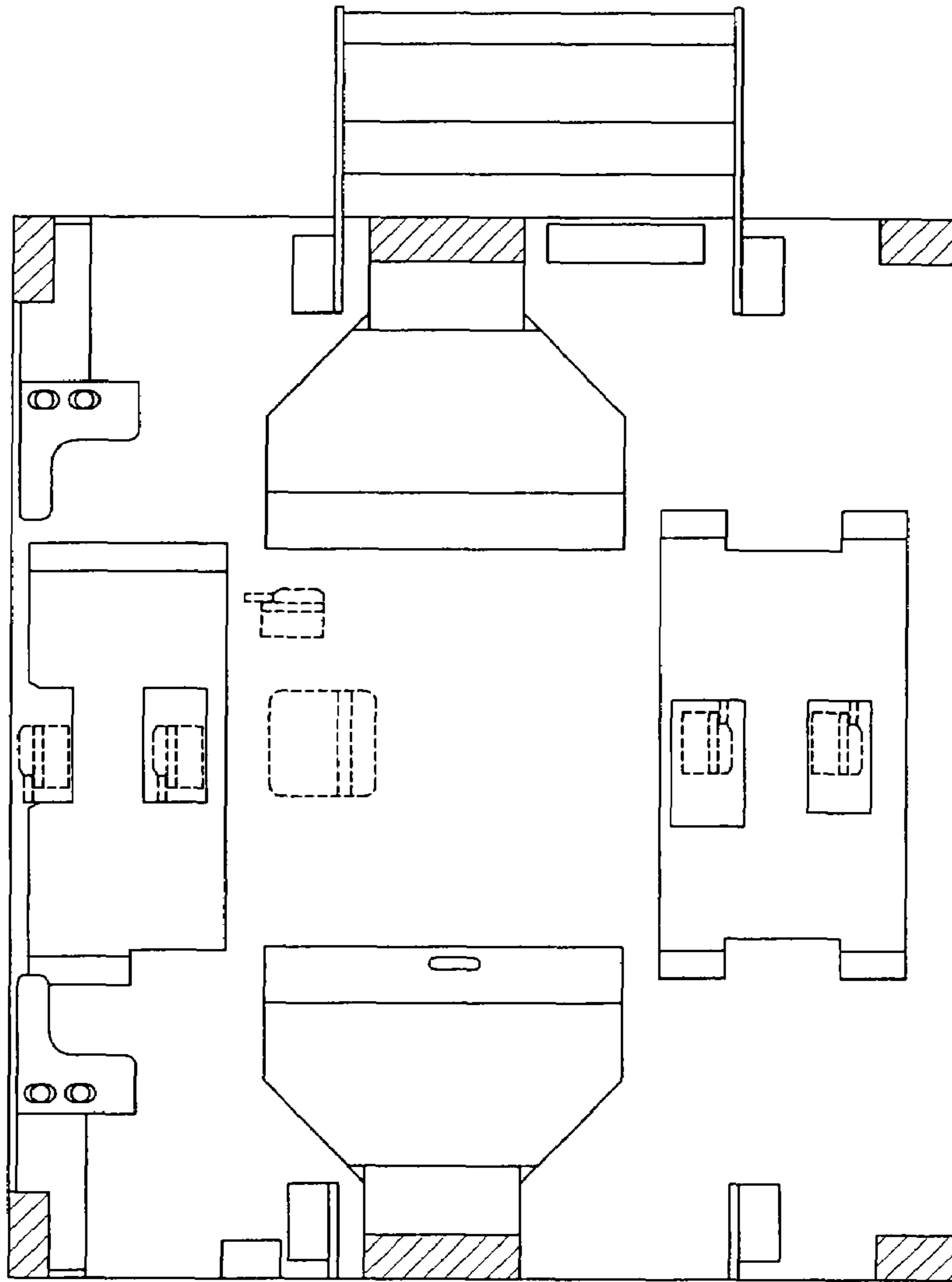


Fig. 7

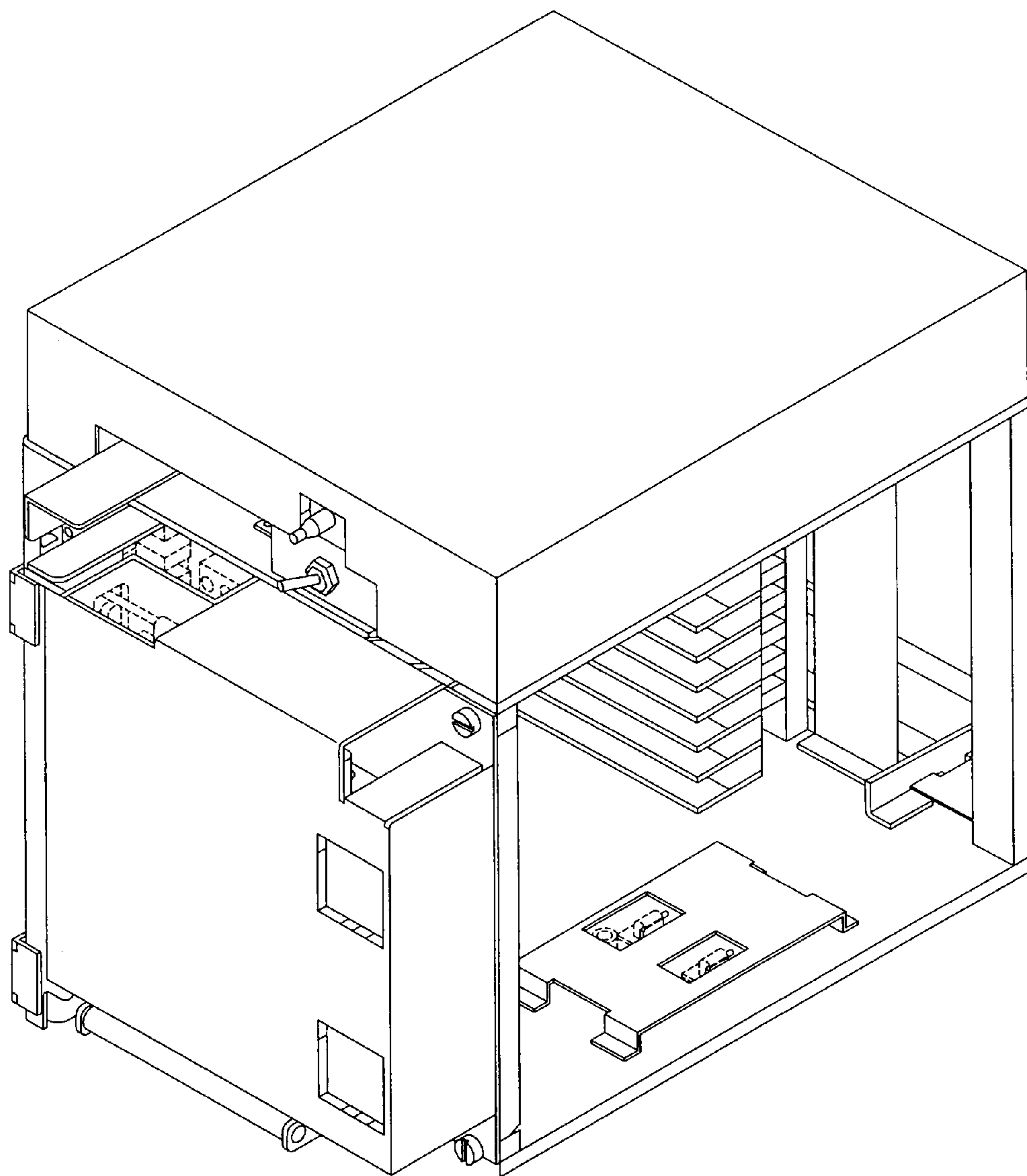


Fig. 8

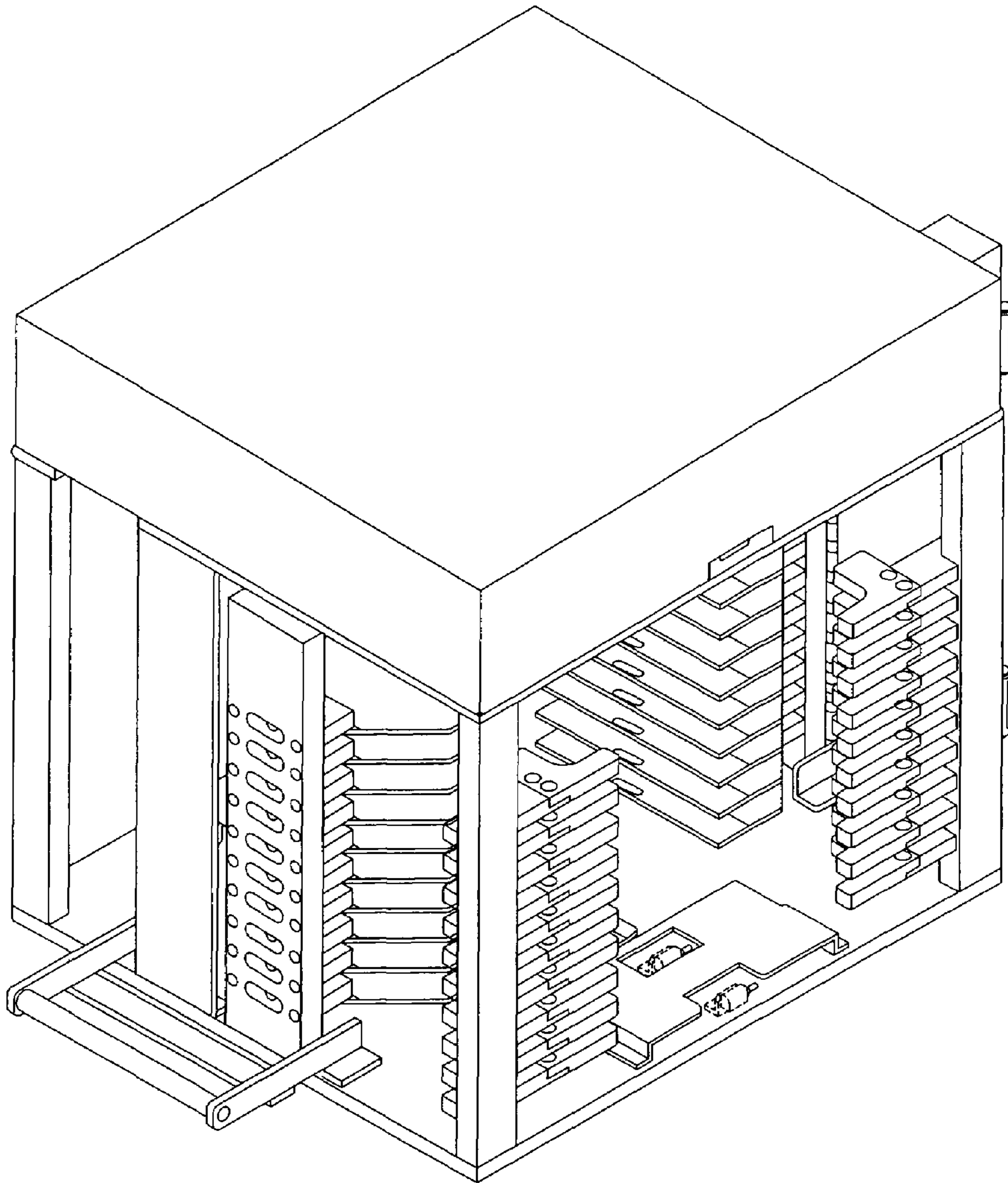


Fig. 9